



Major Ratings and Characteristics

$I_{F(AV)}$	0.5A , 0.8A
V_{RRM}	200-600V
I_{FSM}	30 A
I_R	5.0 μ A
t_{rr}	150nS,250nS
V_F	1.25V
T_j max.	150 °C

Features

- Low profile space
- Ideal for automated placement
- Glass passivated chip junction
- Low forward voltage drop
- Low leakage current
- High forward surge capability
- High temperature soldering:
260°C/10 seconds at terminals
- Component in accordance to
RoHS 2002/95/1 and WEEE 2002/96/EC

Mechanical Date

- Case: MBF Molded plastic over glass passivated chip
- Terminals: Solder plated, solderable per J-STD-002B and JESD22-B102D
- Polarity: Polarity symbols marked on body

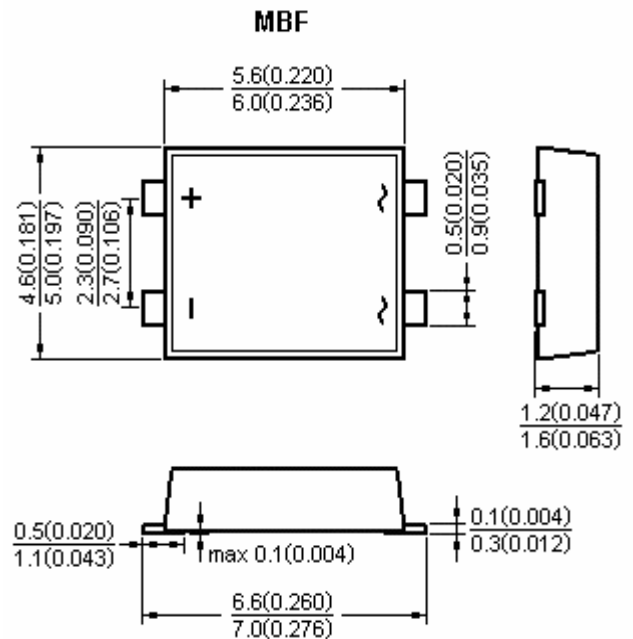
Maximum Ratings & Thermal Characteristics & Electrical Characteristics

($T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)

	Symbol	RMB2F	RMB4F	RMB6F	UNIT
Maximum repetitive peak reverse voltage	V_{RRM}	200	400	600	V
Maximum RMS voltage	V_{RMS}	140	280	420	V
Maximum DC blocking voltage	V_{DC}	200	400	600	V
Maximum average forward output rectified current at $T_A=30\text{ }^\circ\text{C}$ -on glass-epoxy P.C.B (NOTE 1) -on aluminum substrate (NOTE 2)	$I_{F(AV)}$	0.5 0.8			A
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load(JEDEC Method)	I_{FSM}	30			A
Maximum instantaneous forward voltage drop per leg at 0.4A	V_F	1.25			V
Maximum DC reverse current at rated DC blocking voltage per leg $T_A = 25\text{ }^\circ\text{C}$ $T_A = 125\text{ }^\circ\text{C}$	I_R	5.0 100			μ A
Maximum reverse recovery time at $I_F = 0.5\text{ A}$, $I_R = 1.0\text{ A}$, $I_{rr} = 0.25\text{ A}$	t_{rr}	150		250	nS
Typical junction capacitance per leg at 4.0 V ,1MHz	C_J	13			p F
Thermal resistance per leg (NOTE 1) (NOTE 2) (NOTE 1)	$R_{\theta JA}$	85			$^\circ\text{C}/\text{W}$
	$R_{\theta JA}$	70			
	$R_{\theta JL}$	20			
Operating junction and storage temperature range	T_J, T_{STG}	-55 to +150			$^\circ\text{C}$

NOTE1:On glass epoxy P.C.B. mounted on 0.05×0.05" (1.3×1.3mm) pads

NOTE2:On aluminum substrate P.C.B. with an area of 0.8×0.8" (20×20mm) mounted on 0.05×0.05" (1.3×1.3mm) solder pad



Dimensions in millimeters and (inches)



Characteristic Curves ($T_A=25\text{ }^\circ\text{C}$ unless otherwise noted)

